Quad Analog Switch/ Multiplexer/Demultiplexer with Separate Analog and Digital Power Supplies

High–Performance Silicon–Gate CMOS

The MC74HC4316A utilizes silicon–gate CMOS technology to achieve fast propagation delays, low ON resistances, and low OFF–channel leakage current. This bilateral switch/multiplexer/ demultiplexer controls analog and digital voltages that may vary across the full analog power–supply range (from V_{CC} to V_{EE}).

The HC4316A is similar in function to the metal–gate CMOS MC14016 and MC14066, and to the High–Speed CMOS HC4066A. Each device has four independent switches. The device control and Enable inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs. The device has been designed so that the ON resistances (R_{ON}) are much more linear over input voltage than R_{ON} of metal–gate CMOS analog switches. Logic–level translators are provided so that the On/Off Control and Enable logic–level voltages need only be V_{CC} and GND, while the switch is passing signals ranging between V_{CC} and V_{EE} . When the Enable pin (active–low) is high, all four analog switches are turned off.

Features

- Logic-Level Translator for On/Off Control and Enable Inputs
- Fast Switching and Propagation Speeds
- High ON/OFF Output Voltage Ratio
- Diode Protection on All Inputs/Outputs
- Analog Power–Supply Voltage Range $(V_{CC} V_{EE}) = 2.0$ to 12.0 V
- Digital (Control) Power–Supply Voltage Range (V_{CC} – GND) = 2.0 V to 6.0 V, Independent of V_{EE}
- Improved Linearity of ON Resistance
- Chip Complexity: 66 FETs or 16.5 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free and are RoHS Compliant



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D SUFFIX CASE 751B

PIN ASSIGNMENT

			_
X _A [1●	16] v _{cc}
Y _A [2	15	A ON/OFF CONTROL
Y _B [3	14	D ON/OFF CONTROL
X _B [4	13	
B ON/OFF CONTROL	5	12] Y _D
C ON/OFF	6	11] Y _C
ENABLE [7	10] x _c
GND [8	9	D V _{EE}
			4

MARKING DIAGRAM



А	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW. W	= Work Week

V, W = Work Week

G

= Pb–Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74HC4316ADR2G	SOIC-16 (Pb-Free)	2500/ Tape&Reel
NLV74HC4316ADR2G*	SOIC-16 (Pb-Free)	2500/ Tape&Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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FUNCTION TABLE

Inp	State of Analog	
Enable	On/Off Control	Switch
L L H	H L X	On Off Off

X = Don't Care.

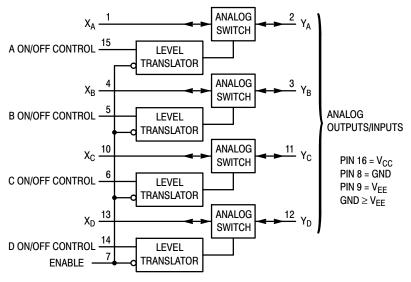




Figure 1. Logic Diagram

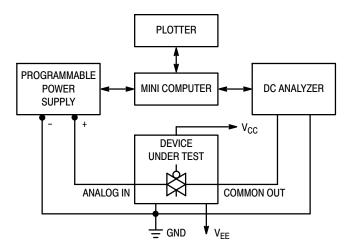


Figure 2. On Resistance Test Set-Up

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Positive DC Supply Voltage (Ref. to GND) (Ref. to V _{EE})	-0.5 to +7.0 -0.5 to +14.0	V
V_{EE}	Negative DC Supply Voltage (Ref. to GND)	-7.0 to +0.5	V
V _{IS}	Analog Input Voltage	V _{EE} – 0.5 to V _{CC} + 0.5	V
V _{in}	DC Input Voltage (Ref. to GND)	–0.5 to V _{CC} + 0.5	V
I	DC Current Into or Out of Any Pin	±25	mA
P _D	Power Dissipation in Still Air SOIC Package*	500	mW
T _{stg}	Storage Temperature	– 65 to + 150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open. I/O pins must be connected to a properly terminated line or bus.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

*Derating - SOIC Package: -7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage (Ref. to GND)		2.0	6.0	V
V_{EE}	Negative DC Supply Voltage (Ref. to GND)		-6.0	GND	V
V _{IS}	Analog Input Voltage		V_{EE}	V _{CC}	V
V _{in}	Digital Input Voltage (Ref. to GND)		GND	V _{CC}	V
V _{IO} *	Static or Dynamic Voltage Across Switch		-	1.2	V
T _A	Operating Temperature, All Package Types		-55	+125	°C
t _r , t _f	(Control or Enable Inputs) V _{CC} (Figure 10) V _{CC}	f = 2.0 V f = 3.0 V f = 4.5 V f = 6.0 V	0 0 0 0	1000 600 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

*For voltage drops across the switch greater than 1.2 V (switch on), excessive V_{CC} current may be drawn; i.e., the current out of the switch may contain both V_{CC} and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

				Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	v _{cc} v	–55 to 25°C	≤ 85°C	≤ 125°C	Unit
V _{IH}	Minimum High-Level Voltage, Control or Enable Inputs	R _{on} = Per Spec	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V _{IL}	Maximum Low–Level Voltage, Control or Enable Inputs	R _{on} = Per Spec	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
l _{in}	Maximum Input Leakage Current, Control or Enable Inputs	$V_{in} = V_{CC} \text{ or GND}$ $V_{EE} = -6.0 \text{ V}$	6.0	±0.1	±1.0	±1.0	μΑ
ICC	Maximum Quiescent Supply Current (per Package)		6.0 6.0	2 4	20 40	40 160	μΑ

					Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	V _{CC} V	V _{EE} v	–55 to 25°C	≤ 85°C	≤ 125°C	Unit
R _{on}	Maximum "ON" Resistance	$\begin{array}{l} V_{in} = V_{IH} \\ V_{IS} = V_{CC} \text{ to } V_{EE} \\ I_S \leq 2.0 \text{ mA (Figure 2)} \end{array}$	2.0* 4 5 4.5 6.0	0.0 0.0 -4.5 -6.0	- 160 90 90	- 200 110 110	- 240 130 130	Ω
		$ \begin{array}{l} V_{in} = V_{IH} \\ V_{IS} = V_{CC} \text{ or } V_{EE} \text{ (Endpoints)} \\ I_{S} \leq 2.0 \text{ mA (Figure 2)} \end{array} $	2.0 4.5 4.5 6.0	0.0 0.0 -4.5 -6.0	- 90 70 70	- 115 90 90	- 140 105 105	
ΔR_{on}	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Package	$\label{eq:Vin} \begin{array}{l} V_{in} = V_{IH} \\ V_{IS} = 1/2 \; (V_{CC} - V_{EE}) \\ I_{S} \leq 2.0 \; \text{mA} \end{array}$	2.0 4.5 4.5 6.0	0.0 0.0 4.5 6.0	- 20 15 15	- 25 20 20	- 30 25 25	Ω
I _{off}	Maximum Off–Channel Leakage Current, Any One Channel	$V_{in} = V_{IL}$ $V_{IO} = V_{CC} \text{ or } V_{EE}$ Switch Off (Figure 3)	6.0	-6.0	0.1	0.5	1.0	μΑ
I _{on}	Maximum On–Channel Leakage Current, Any One Channel	$V_{in} = V_{IH}$ $V_{IS} = V_{CC}$ or V_{EE} (Figure 4)	6.0	-6.0	0.1	0.5	1.0	μΑ

DC ELECTRICAL CHARACTERISTICS Analog Section (Voltages Referenced to VEE)

*At supply voltage (V_{CC} – V_{EE}) approaching 2.0 V the analog switch–on resistance becomes extremely non–linear. Therefore, for low–voltage operation, it is recommended that these devices only be used to control digital signals.

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Control or Enable $t_r = t_f = 6$ ns, $V_{EE} = GND$)

				Gua	aranteed Li	mit	
Symbol	Parameter		v _{cc} v	–55 to 25°C	≤ 85°C	≤ 125°C	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Analog Input to Analog (Figures 8 and 9)	g Output	2.0 4.5 6.0	40 6 5	50 8 7	60 9 8	ns
t _{PLZ} , t _{PHZ}	Maximum Propagation Delay, Control or Enable to A (Figures 10 and 11)	nalog Output	2.0 4.5 6.0	130 40 30	160 50 40	200 60 50	ns
t _{PZL} , t _{PZH}	Maximum Propagation Delay, Control or Enable to A (Figures 10 and 11)	nalog Output	2.0 4.5 6.0	140 40 30	175 50 40	250 60 50	ns
С	Maximum Capacitance	ON/OFF Control and Enable Inputs	-	10	10	10	pF
	С	ontrol Input = GND Analog I/O Feedthrough		35 1.0	35 1.0	35 1.0	

		Typical @ 25°C, V _{CC} = 5.0 V	
C _{PD}	Power Dissipation Capacitance (Per Switch) (Figure 13)*	15	рF
411 14			

*Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

ADDITIONAL APPLICATION CHARACTERISTICS (GND = 0 V)

Symbol	Parameter	Test Conditions	V _{CC} V	V _{EE} V	Limit* 25°C	Unit
BW	Maximum On–Channel Bandwidth or Minimum Frequency Response (Figure 5)	$ f_{in} = 1 \text{ MHz Sine Wave} \\ Adjust f_{in} \text{ Voltage to Obtain 0 dBm at V}_{OS} \\ Increase f_{in} \text{ Frequency Until dB Meter} \\ Reads -3 \text{ dB} \qquad \qquad$	2.25 4.50 6.00	-2.25 -4.50 -6.00	150 160 160	MHz
-	Off–Channel Feedthrough Isolation (Figure 6)		2.25 4.50 6.00	-2.25 -4.50 -6.00	-50 -50 -50	dB
		f_{in} = 1.0 MHz, R_L = 50 Ω , C_L = 10 pF	2.25 4.50 6.00	-2.25 -4.50 -6.00	-40 -40 -40	
-	Feedthrough Noise, Control to Switch (Figure 7)	$ \begin{split} V_{in} &\leq 1 \text{ MHz Square Wave } (t_r = t_f = 6 \text{ ns}) \\ \text{Adjust } R_L \text{ at Setup so that } I_S = 0 \text{ A} \\ R_L = 600 \ \Omega, \ C_L = 50 \text{ pF} \end{split} $	2.25 4.50 6.00	-2.25 -4.50 -6.00	30 65 100	mV _{PP}
		$R_L = 10 \text{ k}\Omega, C_L = 10 \text{ pF}$	2.25 4.50 6.00	-2.25 -4.50 -6.00	60 130 200	
-	Crosstalk Between Any Two Switches (Figure 12)		2.25 4.50 6.00	-2.25 -4.50 -6.00	-70 -70 -70	dB
		f_{in} = 1.0 MHz, R_L = 50 Ω , C_L = 10 pF	2.25 4.50 6.00	-2.25 -4.50 -6.00	80 80 80	
THD	Total Harmonic Distortion (Figure 14)	$\label{eq:fin} \begin{array}{l} f_{in} = 1 \text{ kHz}, \text{R}_{L} = 10 \text{ k}\Omega, \text{C}_{L} = 50 \text{ pF} \\ \text{THD} = \text{THD}_{Measured} - \text{THD}_{Source} \\ \text$	2.25 4.50 6.00	-2.25 -4.50 -6.00	0.10 0.06 0.04	%

*Limits not tested. Determined by design and verified by qualification.

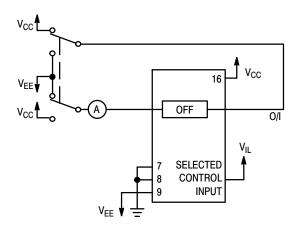
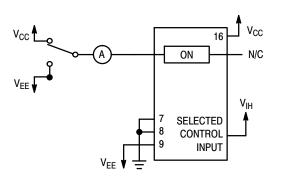
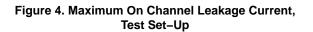
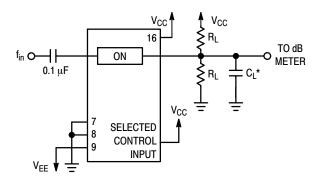


Figure 3. Maximum Off Channel Leakage Current, Any One Channel, Test Set–Up

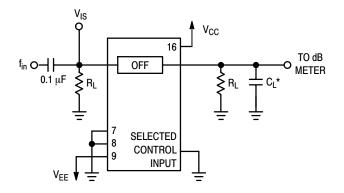






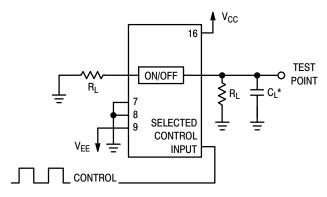
*Includes all probe and jig capacitance.

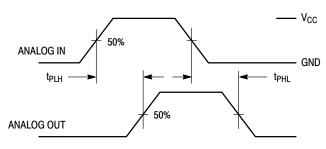
Figure 5. Maximum On–Channel Bandwidth Test Set–Up



*Includes all probe and jig capacitance.

Figure 6. Off–Channel Feedthrough Isolation, Test Set–Up

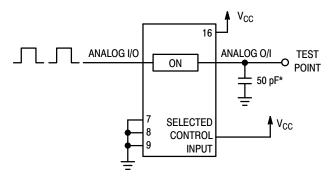






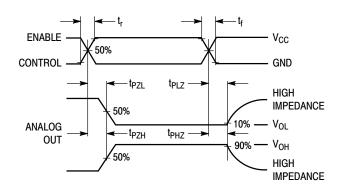
*Includes all probe and jig capacitance.

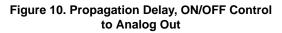
Figure 7. Feedthrough Noise, Control to Analog Out, Test Set–Up

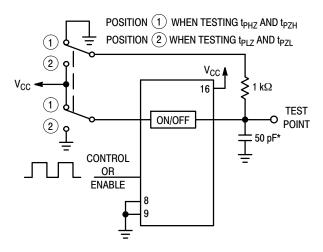


*Includes all probe and jig capacitance.

Figure 9. Propagation Delay Test Set-Up







*Includes all probe and jig capacitance.

Figure 11. Propagation Delay Test Set–Up

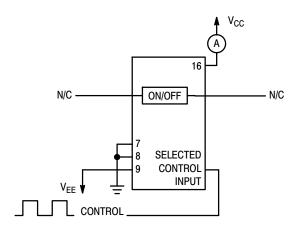
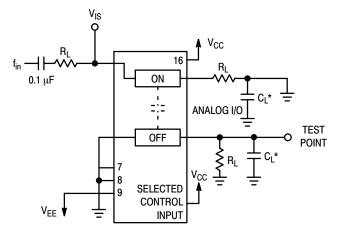
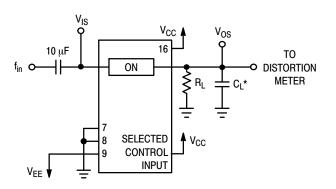


Figure 13. Power Dissipation Capacitance Test Set–Up



*Includes all probe and jig capacitance.

Figure 12. Crosstalk Between Any Two Switches, Test Set–Up (Adjacent Channels Used)



*Includes all probe and jig capacitance.

Figure 14. Total Harmonic Distortion, Test Set-Up

APPLICATIONS INFORMATION

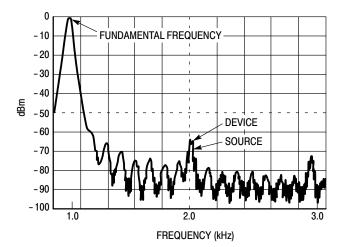


Figure 15. Plot, Harmonic Distortion

The Enable and Control pins should be at V_{CC} or GND logic levels, V_{CC} being recognized as logic high and GND being recognized as a logic low. Unused analog inputs/outputs may be left floating (not connected). However, it is advisable to tie unused analog inputs and outputs to V_{CC} or V_{EE} through a low value resistor. This minimizes crosstalk and feedthrough noise that may be picked up by the unused I/O pins.

The maximum analog voltage swings are determined by the supply voltages V_{CC} and V_{EE} . The positive peak analog voltage should not exceed V_{CC} . Similarly, the negative peak analog voltage should not go below V_{EE} . In the example below, the difference between V_{CC} and V_{EE} is 12 V. Therefore, using the configuration in Figure 16, a maximum analog signal of twelve volts peak-to-peak can be controlled.

When voltage transients above V_{CC} and/or below V_{EE} are anticipated on the analog channels, external diodes (Dx) are recommended as shown in Figure 17. These diodes should be small signal, fast turn–on types able to absorb the maximum anticipated current surges during clipping. An alternate method would be to replace the Dx diodes with MOSORBs (MOSORB[®] is an acronym for high current surge protectors). MOSORBs are fast turn–on devices ideally suited for precise dc protection with no inherent wear out mechanism.

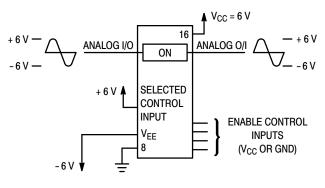


Figure 16.

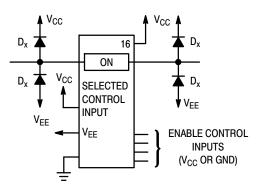
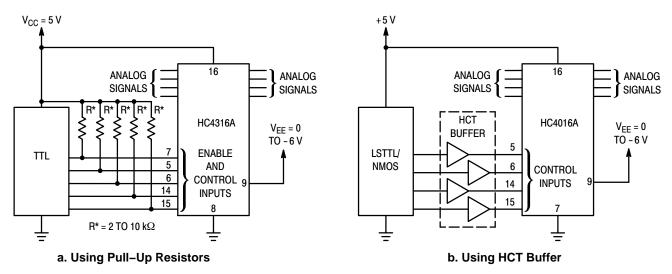
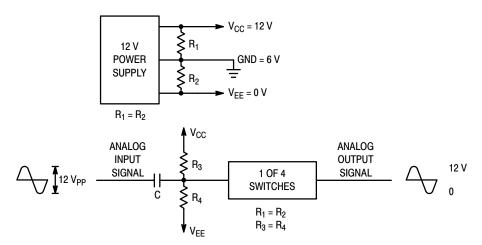
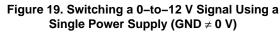


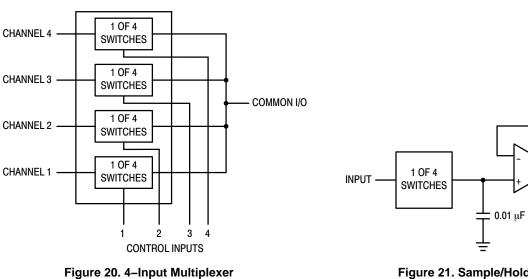
Figure 17. Transient Suppressor Application













OUTPUT

LF356 OR

EQUIVALENT

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